

EMI Shielding Paste

Spraying directly onto semiconductor packages and plastic housing

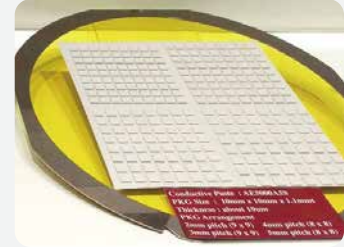
Applications

Semiconductor packages

Thin conductive paste layer on 3D surfaces by spray coating.



After deposition and curing



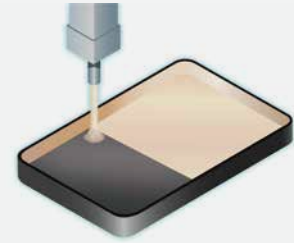
After deposition and curing

Housing

Deposit to electronics device plastic housing by spray coating.



After deposition and curing



Spray coating

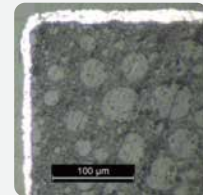
Features

- Excellent shielding effectiveness over 70dB
- Excellent adhesion to various surfaces

Surface of coated PKG



Cross-section



Product line-up & properties

Product		AE5000A5-12GS	AE5000W Series	AE5000L-73	
Type		Highly adhesive	Thin layer	For housing	
		For semiconductor packages			
Viscosity	E type, 10rpm* mPa·s	200 ± 100			
Curing conditions	Pre-curing	100°C × 10min.		—	
	Post-curing	170°C × 50min.	150°C × 50min.	80°C × 120min. / 100°C × 60min.	
Volume resistivity (Representative value)		Ω·cm	5.0E-05	2.0E-05	1.0E-04

*Cone-plate viscometer CP-40 10rpm

